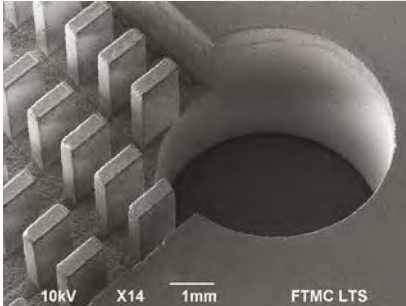


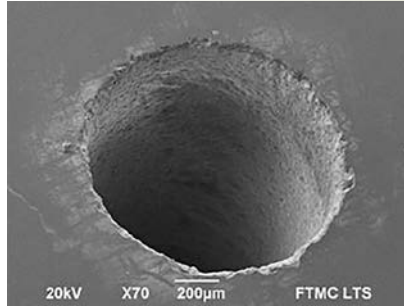
Material processing samples

GLASS MILLING



Surface chipping <100 μm, sidewall roughness <2 μm. Courtesy of FTMC.

GLASS DRILLING



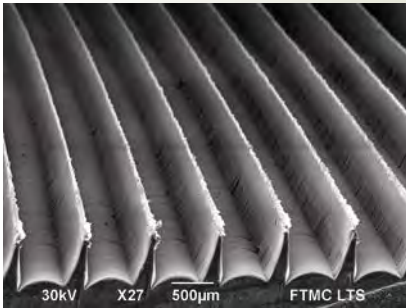
Surface chipping <100 μm, sidewall roughness <2 μm. Courtesy of FTMC.

POLYAMIDE DRILLING



Drilling of 65 μm holes in 0.8 mm PI

TEFLON ABLATION



Teflon (PTFE) ablation. Courtesy of FTMC.

NICKEL ABLATION



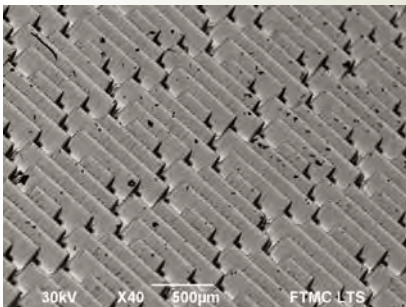
Ablation of 50 μm nickel layer from a ceramic substrate.

COPPER ABLATION



Copper removal from PCB with down to <20 μm resolution.

SURFACE STRUCTURING



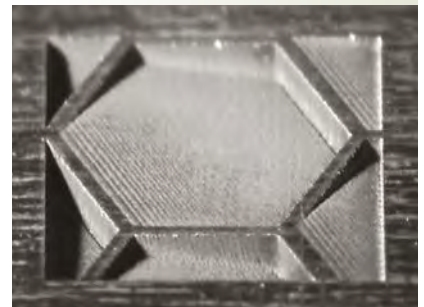
"Shark skin" surface structuring. Courtesy of FTMC.

STAINLESS STEEL MARKING



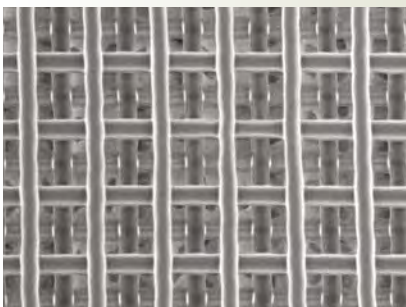
Highly resistant stainless steel black marking

COPPER ABLATION



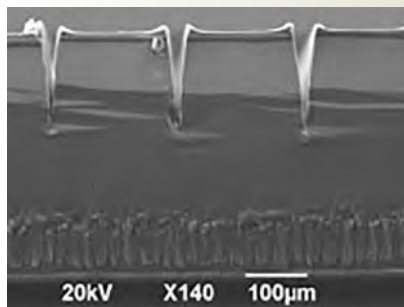
Surface roughness of 0.2 μm. Courtesy of Leibnitz IOM.

PHOTOPOLYMERIZATION



Courtesy of Workshop of Photonics.

SILICON SCRIBING



Courtesy of FTMC.

COPPER DEEP 3D ENGRAVING



Courtesy of FTMC.